

WAFER POLISHING SYSTEM, AND LOADING METHOD AND USE METHOD THEREFOR

ABSTRACT

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Disclosed in the present invention is a wafer polishing system, comprising: a wafer transfer apparatus that comprises a fixing base and a carrying table, the fixing base being capable of driving the carrying table to move in a wafer transmission channel along an X-axis direction; and a polishing module that is disposed at a side edge of the wafer transmission channel and is capable
10 of obtaining a wafer from the carrying table for polishing. A connecting mechanism is provided between the fixing base and the carrying table, the connecting mechanism has a portion connected to the fixing base and a portion connected to the carrying table; when the two portions of the connecting mechanism are in connection, the carrying table and the fixing base are positionlimited, and the connecting mechanism can move in the plane where the X axis and a Y axis are located,
15 so as to drive the carrying table to move to a target position. Also disclosed in the present invention is a loading method for the wafer polishing system. Further disclosed in the present invention is a use method for the wafer polishing system. According to the present invention, the movement of the carrying table to the target position is effectively ensured, superposition adjustment is performed in two dimensions, and the connection range is wide; connection and position limiting
20 can be performed in different processes, and the application is flexible.

FIG. 1